

#### **Features**

- Wide Input Voltage Range: 3V~28V
- Adjustable 0.8V~20V Output Range
- Wide output load range: 0 to 8A
- ±1% Output Voltage Accuracy over Line and Load
- Constant-on-time control scheme for fast transient and high Efficiency
- Programmable Operation Frequency from 100kHz to 600kHz
- Integrated 18 mΩ at LDO=5V N-Channel
   MOSFET For High Side
- Integrated 9.5 mΩ at LDO=5V N-Channel
   MOSFET For Low Side
- Selectable Forced PWM or automatic PFM/PWM mode
- Under-Voltage Protection
- Over-Voltage Protection
- FB Short Protection
- Internal 5V Pre-regulator
- External Adjustable Soft-Start and Soft-Step
- Over Temperature Protection
- Programmable Over Current Protection
- TQFN23-4x4 package
- Green Product (RoHS, Lead Free, Halogen-Free Compliant)

# **Applications**

- Notebook computers
- CPU core/IO Supplies
- Chip/RAM Supplies

# **General Description**

The GS92A3 is small size chip with a relative constant on-time synchronous buck switching converter suitable for applications in notebook computers and other battery operated portable devices. Features include wide input voltage range, high efficiency and fast dynamic response The GS92A3 has a unique power save mode, which can save battery power supply by decreasing frequency when load current falls down below preset critical current point.

The fast dynamic transient response means that buck converter applications based on GS92A3 will provide about 109ns-order response to load when output voltage falls down or rises up. The frequency will increase or decrease to meet the change in output load. Moreover, the GS92A3 will take the same method to regulate the output voltage when input voltage changes. When transient response regulated, the converter will maintain a new steady-state operation. Both the transient response state and the new state, the GS92A3 always has the same on-time width.

The GS92A3 is suitable for the solutions which have the output voltage between 0.8V and 20V. An external setting resistor and output voltage can set the on-time width, duty-cycle and frequency for the converter. The integrated gate drivers feature adaptive shoot-through protection, fast signal transmission. Additional features include current limit, soft-start, over-voltage and under-voltage protection and soft discharge upon shutdown. The GS92A3 is available in package TQFN23-4x4.

This document is GStek's confidential information. Anyone having confidential obligation to GStek shall keep this document confidential. Any unauthorized disclosure or use beyond authorized purpose will be considered as violation of confidentiality and criminal and civil liability will be asserted.



# **Typical Application**

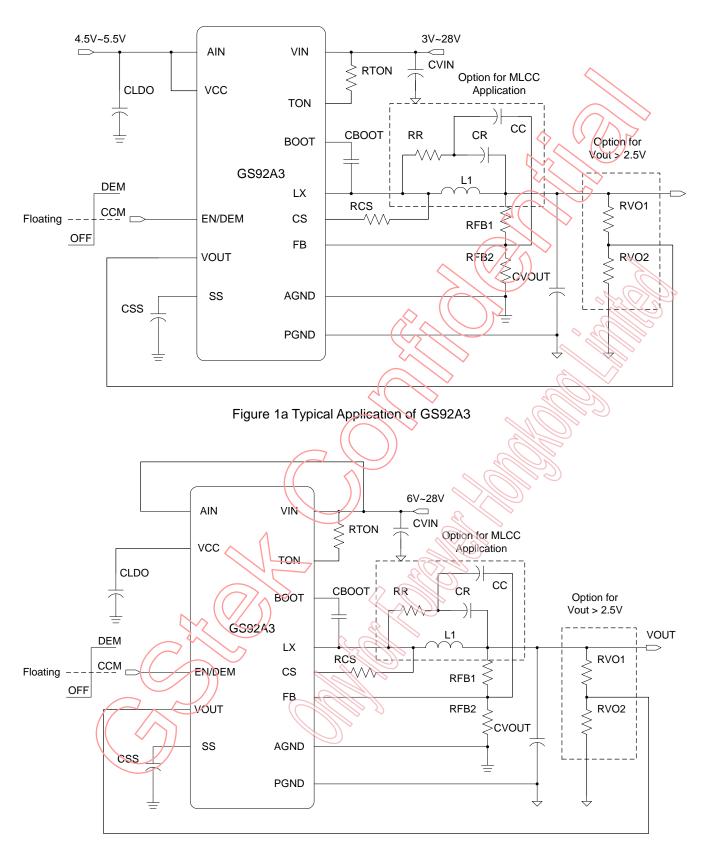
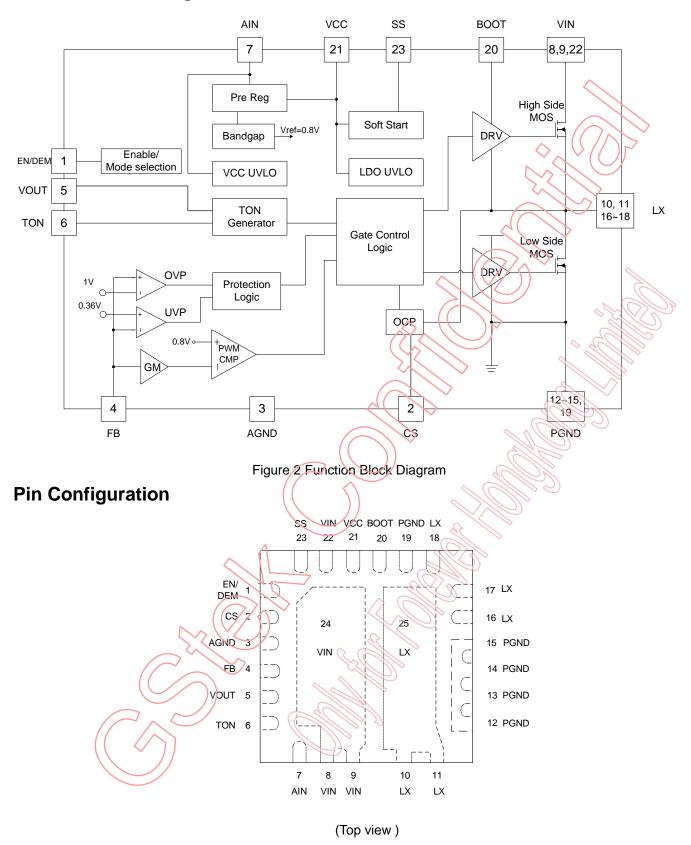


Figure 1b Typical Application of GS92A3



# **Function Block Diagram**



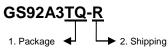


# **Pin Descriptions**

No.	Name	I/O	Description
1	EN/DEM	I	Buck Enable Control Pin. EN=Low, Shutdown; EN=High, Auto-DEM Mode; EN=Floating, Forced CCM.
2	CS	I/O	Current Limit Detecting Input Pin. Connect LX Pin though an external resistor to set the current limit threshold.
3	AGND	0	Signal GND.
4	FB	I	Feedback Input. Adjust the output voltage with a resistive voltage-divider between the regulator's output and AGND.
5	VOUT	I	VOUT Pin offers the output information to the chip, in order to make the frequency setting more accuracy. When OVP condition occurs, through this pin discharge the energy of vout capacitor.
6	TON	I/O	On-Time Setting Input. Connect a resistor between VIN and TON to set the on time width.
7	AIN	I/O	Supply Input for internal analog circuitry.
8, 9, 22,24	VIN	I	Supply Input. VIN is the regulator input. All VIN pins must be connected together.
10, 11, 16~18,25	LX	I/O	Upper Driver Floating Ground for Buck Controller. Connect to an external inductor.
12~15, 19	PGND	0	Power Ground.
20	воот	1	Bootstrap Capacitor Connection. Connect a capacitor between BOOT and LX Pin.
21	VCC	1/0	Internal Linear Regulator Output.
23	SS	7 NO	Soft-Start Time Setting Pin. Connect a capacitor between SS and AGND to set the soft-start time.



# Ordering Information



No	Item	Contents	
1	Package	TQ:TQFN23-4x4	
2	Shipping	R: Tape & Reel	

Example: GS92A3 TQFN23-4x4 Tape & Reel ordering information is "GS92A3TQ-R"

# **Absolute Maximum Rating (Note 1)**

Parameter	Symbol	Limits	Units
VIN, AIN to GND	V <sub>IN</sub> , V <sub>AIN</sub>	-0.3 ~ 30	
TON to GND	V <sub>TON</sub>	-0.3 ~ 30	\ \ \
VCC to GND	V <sub>cc</sub>	-0.3 ~ 6	V
EN/DEM to GND	VENDEM	-0.3 ~ 30	V
VOUT, FB to GND	$V_{\text{OUT}}, V_{\text{FB}}$	-0.3 ~ 6	V
BOOT Voltage	V <sub>BOQT-GND</sub>	-0.3 ~ 40	V
BOOT to LX Voltage	V <sub>BOOT-LX</sub>	-0.3 ~ 6	V
LX to GND DC	V	-0.7~30	V
<200ns	$))$ $V_{LX}$	-8 ~ 32	V
Package Power Dissipation at T <sub>A</sub> ≤25°C	P <sub>D_TQFN23-4x4</sub>	3546	mW
Junction Temperature	TJ	- 45 ~ 150	°C
Storage Temperature	T <sub>STG</sub>	- 55 ~ 150	°C
Lead Temperature (Soldering) 10S	TLEAD	260	°C
ESD (Human Body Mode) (Note 2)	V <sub>ESD_HBM</sub>	2K	V
ESD (Machine Mode) (Note 2)	VESD_MM	200	V



# **Thermal Information (Note 3)**

Parameter	Symbol	Limits	Units
Thermal Resistance Junction to Ambient	$\theta_{JA\_TQFN23\text{-}4x4}$	28.2	°C/W

**Recommend Operating Condition (Note 4)** 

Parameter	Symbol	Limits	Units
VIN to GND (Note 5)	$V_{IN}$	3~28	V
AIN to GND (Note 5)	$V_{AIN}$	6~28	V
VCC to GND	$V_{VCC}$	4.5~5.5	V
EN/DEM to GND	$V_{\text{EN/DEM}}$	V <sub>EN/DEM</sub> = V <sub>AIN</sub>	٧
Junction Temperature	$T_J$	-40 ~125	°C
Ambient Temperature	$T_A$	-40 ~ 85	Çe

# **Electrical Characteristics**

 $(R_{TON}=300 KOhm, V_{IN}=12 V, V_{OUT}=1.2 V, EN/DEM=V_{IN}, T_A=25 °C, unless otherwise specified)$ 

Parameter	Symbol	Conditions	Min	Тур	Max	Units
Supply Voltage (VAIN)				2		
Under voltage lock out	V			5.5		V
(Rising)	V <sub>AIN_UVLO</sub>		(			V
UVLO Hysteresis	V <sub>AIN_UVLOHYS</sub>			0.2		V
5V Pre-regulator (Vvcc)	\					
Output Voltage	V <sub>VCC</sub>			5.15		V
Under voltage lock out	Vvcc_uvic_			4.15		V
(Rising) UVLO Hysteresis	V <sub>VCC_UVLOHYS</sub>			0.3		V
Reference Voltage						
FB Reference Voltage	V <sub>FB</sub>	V <sub>VCC</sub> =5V		0.8		V
Enable Logic						
EN Logic Low Voltage	$V_{EN_L}$	EN Falling			0.6	V
EN Floating Voltage		VIN Power On, Stable		2.2		V
EN Floating vonage	$V_{EN_{F}}$	State(Forced CCM)		۷.۷		V
EN Logic High Voltage	$V_{EN\_H}$	EN Rising(DEM)	3.1			V
Current Parameters						
Quiescent	l <sub>Q</sub>	FB=0.85V, VIN=12V		830		uA



Soft start current						1	
Shutdown Current	Soft start current	I <sub>SS</sub>	Vss=0		10		uA
EN=0, I(EN)   -2   -1   UA			EN=0, I(VIN)		4		uA
Logic Input Current   I <sub>EN</sub>	Shutdown Current	I <sub>SHTDN</sub>	EN=0, I(TON)			0.01	uA
Logic Input Current   I_{EN			EN=0, I(EN)	-2	-1	^	uA
EN=0V	Lagia Input Current		EN=12V		13		uA
On-Time $T_{ON} = \begin{bmatrix} V_{IN}=12V, V_{FB}=0.79V, \\ R_{TON}=300K, \\ V_{OUT}=1.2V \end{bmatrix}$ Minimum On-Time $T_{ON\_Min} = \begin{bmatrix} V_{IN}=12V, V_{FB}=0.79V, \\ R_{TON}=1K, V_{OUT}=1.2V \end{bmatrix}$ Minimum Off-Time $T_{OFFMIN} = \begin{bmatrix} V_{IN}=12V, V_{FB}=0.79V, \\ R_{TON}=300K \end{bmatrix}$ High Side MOS RDSON $R_{DSH} = \begin{bmatrix} R_{DSH} \\ R_{TON}=300K \end{bmatrix}$ High Side Leakage $I_{LEAKH} = \begin{bmatrix} R_{DSH} \\ R_{DSH} \end{bmatrix}$ Low Side MOS RDSON $R_{DSL} = \begin{bmatrix} R_{DSH} \\ R_{DSH} \end{bmatrix}$ VCC-GND=5V $ \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ CS Set Source Current $I_{CS} = \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ CS Set Source Current $I_{CS} = \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ On the bias of TA=25°C $ \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ Current Limit 1 (Rising) $I_{LIM1} = \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ GND=LX, RCS=18K $ \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ 300 ns $ \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ ns $ \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$ On the bias of TA=25°C $ \begin{bmatrix} R_{DS} \\ R_{DS} \end{bmatrix}$	Logic input Current	IEN	EN=0V	-2	-1 /		uA
On-Time         Ton         R <sub>ToN</sub> =300K, V <sub>OUT</sub> =1.2V         300         ns           Minimum On-Time         Ton_Min         V <sub>IN</sub> =12V, V <sub>FB</sub> =0.79V, R <sub>ToN</sub> =1K, V <sub>OUT</sub> =1.2V         100         ns           Minimum Off-Time         Toffmin         V <sub>IN</sub> =12V, V <sub>FB</sub> =0.79V, R <sub>ToN</sub> =300K         440         ns           High Side MOS RDSON         R <sub>DSH</sub> BOOT-LX=5V         18         mohms           High Side Leakage         I <sub>LEAKH</sub> 10         uA           Low Side MOS RDSON         R <sub>DSL</sub> VCC-GND=5V         9.5         mohms           Low Side Leakage         I <sub>LEAKL</sub> 10         uA           Current Sensing           CS Set Source Current         I <sub>CS</sub> V <sub>CS=1</sub> V         20         uA           ICS current temperature coefficient         TCS         On the bias of TA=25°C         4900         ppm/°C           Current Limit 1 (Rising)         I <sub>LIM1</sub> GND-LX, RCS=18K         324         360         396         mV	System Time & Driver On			$\Diamond_{\wedge}$	1(//	7	
Vout = 1.2 V			V <sub>IN</sub> =12V, V <sub>FB</sub> =0.79V,		M		
Minimum On-Time         T <sub>ON_Min</sub> V <sub>IN</sub> =12V, V <sub>FB</sub> =0.79V, R <sub>TON</sub> =1.2V         100         ns           Minimum Off-Time         T <sub>OFFMIN</sub> V <sub>IN</sub> =12V, V <sub>FB</sub> =0.79V, R <sub>TON</sub> =300K         440         ns           High Side MOS RDSON         R <sub>DSH</sub> BOOT-LX=5V         18         mohms           High Side Leakage         I <sub>LEAKH</sub> 10         uA           Low Side MOS RDSON         R <sub>DSL</sub> VCC-GND=5V         9.5         mohms           Low Side Leakage         I <sub>LEAKL</sub> 10         uA           Current Sensing           CS Set Source Current         I <sub>CS</sub> V <sub>CS</sub> =1V         20         uA           ICS current temperature coefficient         TCS         On the bias of TA=25°C         4900         ppm/°C           Current Limit 1 (Rising)         I <sub>LIM1</sub> GND=LX, RCS=18K         324         360         396         mV	On-Time	$T_ON$	R <sub>TON</sub> =300K,		300		ns
Minimum On-Time         Ton_Min         Ron=1K, Vout=1.2V         100         ns           Minimum Off-Time         Toffmin         Vin=12V, VfB=0.79V, Ron=300K         440         ns           High Side MOS RDSON         RDSH         BOOT-LX=5V         18         mohms           High Side Leakage         ILEAKH         10         uA           Low Side MOS RDSON         RDSL         VCC-GND=5V         9.5         mohms           Low Side Leakage         ILEAKL         10         uA           Current Sensing         UCS         VCS=1V         20         uA           ICS current temperature coefficient         TCS         On the bias of TA=25°C         4900         ppm/°C           Current Limit 1 (Rising)         ILIM1         GND-LX, RCS=18K         324         360         396         mV			V <sub>OUT</sub> =1.2V	$\lambda$			
Note	Minimum On Time	<b>T</b>	V <sub>IN</sub> =12V, V <sub>FB</sub> =0.79V,		100		
Minimum Off-Time         I OFFMIN         R TON=300K         440         18           High Side MOS RDSON         R DSH         BOOT-LX=5V         18         mohms           High Side Leakage         I LEAKH         10         uA           Low Side MOS RDSON         R DSL         VCC-GND=5V         9.5         mohms           Low Side Leakage         I LEAKL         10         uA           Current Sensing           CS Set Source Current         I CS         VCS=1V         20         uA           ICS current temperature coefficient         TCS         On the bias of TA=25°C         4900         ppm/°C           Current Limit 1 (Rising)         I LIM1         GND-LX, RCS=18K         324         360         396         mV	Minimum On-Time	I ON_Min	R <sub>TON</sub> =1K, V <sub>OUT</sub> =1.2V	(7/	100	4	ns
High Side MOS RDSON  RDSH  High Side Leakage  Low Side MOS RDSON  RDSL  Low Side Leakage  Low Side Lea	Minimum Off Time	<b>-</b>	V <sub>IN</sub> =12V, V <sub>FB</sub> =0.79V,		140	, (	
High Side Leakage  Low Side MOS RDSON  RDSL  VCC-GND=5V  9.5  mohms  Low Side Leakage  ILEAKL  10  uA  Current Sensing  CS Set Source Current  ICS  CURRENT temperature  coefficient  Current Limit 1 (Rising)  ILIM1  GND-LX, RCS=18K  324  360  396  mV	Minimum Off-Time	I <sub>OFFMIN</sub>	R <sub>TON</sub> =300K		440	0 62	) ns
Low Side MOS RDSON  RDSL  VCC-GND=5V  9.5  mohms  Low Side Leakage  ILEAKL  Current Sensing  CS Set Source Current  ICS  VCS=1V  On the bias of TA=25°C  Current Limit 1 (Rising)  ILIM1  GND-LX, RCS=18K  324  360  396  mV	High Side MOS RDSON	R <sub>DSH</sub>	BOOT-LX=5V		18 🖠	Mr.	mohms
Low Side Leakage I <sub>LEAKL</sub> 10 uA  Current Sensing  CS Set Source Current I <sub>CS</sub> V <sub>CS</sub> =1V 20 uA  ICS current temperature coefficient  TCS On the bias of TA=25°C 4900 ppm/°C  Current Limit 1 (Rising) I <sub>LIM1</sub> GND-LX, RCS=18K 324 360 396 mV	High Side Leakage	I <sub>LEAKH</sub>			10		uA
Current Sensing  CS Set Source Current  ICS	Low Side MOS RDSON	R <sub>DSL</sub>	VCC-GND=5√	>	9.5		mohms
CS Set Source Current  ICS	Low Side Leakage	I <sub>LEAKL</sub>			10	22	uA
ICS current temperature coefficient  TCS  On the bias of TA=25°C  4900  ppm/°C  Current Limit 1 (Rising)  I <sub>LIM1</sub> GND-LX, RCS=18K  324  360  396  mV	Current Sensing						
coefficient  TCS On the bias of TA=25°C 4900 ppm/°C  Current Limit 1 (Rising) I <sub>LIM1</sub> GND-LX, RCS=18K 324 360 396 mV	CS Set Source Current	I <sub>CS</sub>	V <sub>CS</sub> =1V		20		uA
Current Limit 1 (Rising) I <sub>LIM1</sub> GND-LX, RCS=18K 324 360 396 mV	ICS current temperature	тоо	041454740500		1000		
	coefficient	108	On the bias of TA=25°C		4900		ppm/°C
Current Limit 2 (Rising)   King   GND-LX RCS-10K   180   200   220   m\/	Current Limit 1 (Rising)	I <sub>LIM1</sub>	GND-LX, RCS=18K	324	360	396	mV
	Current Limit 2 (Rising)	LIM2	GND-LX, RCS=10K	180	200	220	mV
Current Limit 3 (Rising) I <sub>LIM3</sub> GND-LX, RCS=2.5K 35 50 65 mV	Current Limit 3 (Rising)	I <sub>LIM3</sub>	GND-LX, RCS=2.5K	35	50	65	mV
Zero Crossing Threshold V <sub>T,0</sub> GND-LX -10 10 mV	Zero Crossing Threshold	V <sub>T</sub> 0	GND-LX	-10		10	mV
Voltage Fault Protection	Voltage Fault Protection	2	W				
Measure at V <sub>FB</sub> , with		1/2	Measure at V <sub>FB</sub> , with				
UVP Threshold V <sub>UV_TH</sub> respect to reference 45 %	UVP Threshold	V <sub>UV_TH</sub>	respect to reference		45		%
voltage			voltage				
From Enable to UVP		<i></i>	From Enable to UVP		4.0.408		
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	UVP Blank Time	$T_{UV\_B}$	80mV <v<sub>FB<uvp< td=""><td></td><td></td><td></td><td>ms</td></uvp<></v<sub>				ms
Threshold xC <sub>ss</sub>			Threshold		XUSS		
Force V <sub>FB</sub> below UVP		<u>-</u>	Force V <sub>FB</sub> below UVP		00		
UVP Fault Delay T <sub>UV_D</sub> threshold 20 us	LIVD Foult Dalow						

Rev.:0.1 7 Feb-14



OVP Threshold	$V_{OV\_TH}$	Measure at V <sub>FB</sub> , with respect to reference voltage	125		%		
OVP Fault Delay	$T_{OV_D}$	Force V <sub>FB</sub> above OVP Threshold	20		us		
Over Temperature Shutdown							
Thermal Shutdown	т		150	7	°C		
Threshold	$T_{TSDN}$		155		C		
Thermal Shutdown	т		20	$\rightarrow$	Ĵ		
Hysteresis	$T_{HYS\_TSDN}$		20	7	C		
Bootstrap Diode							
Internal Boost Charging	D	VCC to BOOT, 10mA		120	ohms		
Switch On-Resistance	$R_{BT\_D}$	VOC to BOOT, TOTTA		120	OHHIO		

Note 1. Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied.

Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Note 2. Devices are ESD sensitive. Handling precaution recommended.

Note 3.0<sub>JA</sub> is measured in the natural convection at  $T_A=25^{\circ}$ C on a high effective thermal conductivity test board (4 Layers, 2S2P) of JEDEC 51/7 thermal measurement standard

Note 4. The device is not guaranteed to function outside its operating conditions.

Note 5 Recommend the Pulse time<100ns when VIN over than 30V.

**Note 6** If V(BOOT)-V(LX)<4V, a boot diode is recommended.

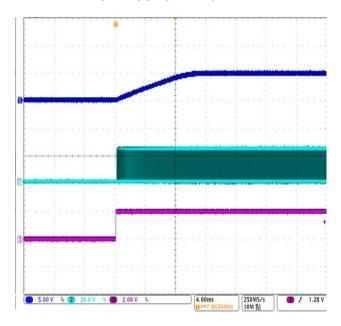
**GStek** 

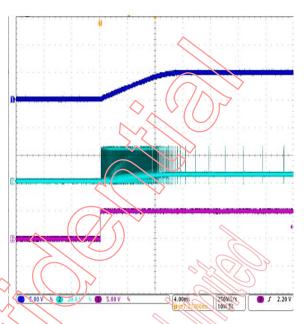
# **Typical Characteristics**

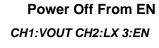


Power on from EN (DEM Mode, No Load)

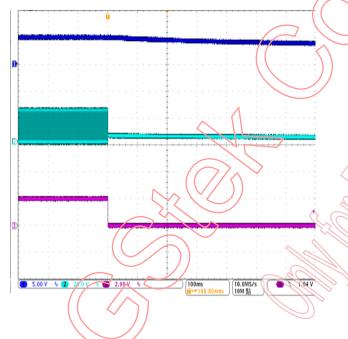
CH1:VOUT CH2:LX 3:EN

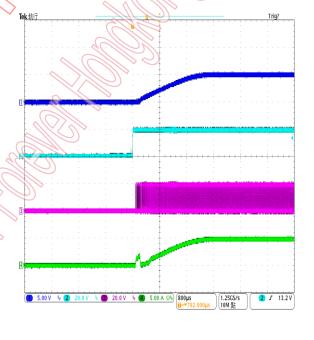




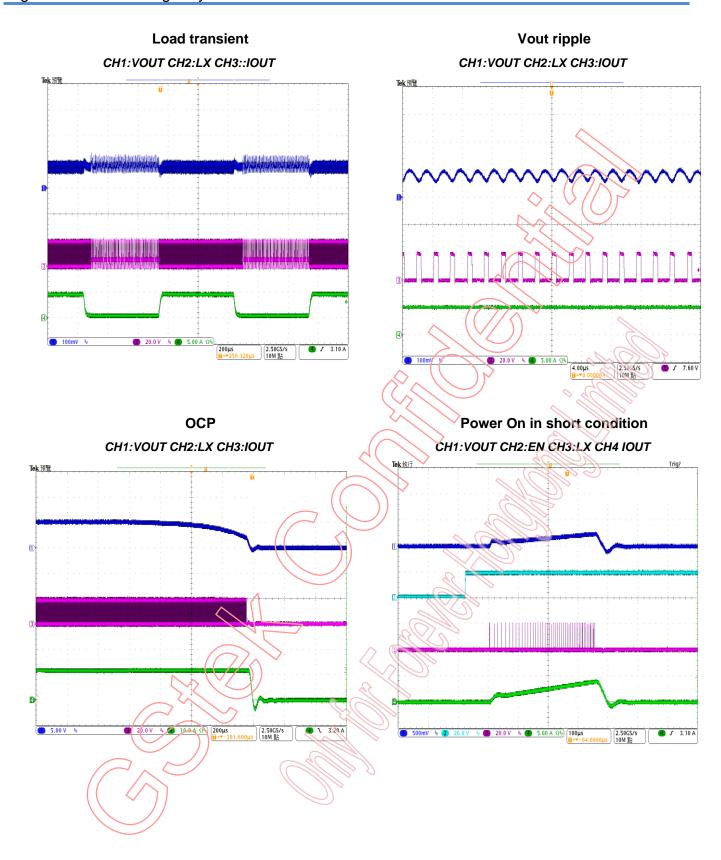


Power on from EN (load=5A)
CH1:VOUT CH2:EN CH3:LX CH4:IOUT















# **Application Information**

The GS92A3 is small size chip with a relative constant on-time synchronous buck switching converter suitable for applications in notebook computers and other battery operated portable devices. Features include wide input voltage range, high efficiency and fast dynamic response.

### **System Clock Generator and PWM Control**

The on-time of GS92A3 can be set by an external setting resistor from input voltage to TON Pin. The converter maintains the on-time width as loop feedback path exists between the GS92A3 converter, low pass filter and voltage divider. For a given input voltage buck application, the feedback maintains the constant on-time width. Due to the constant resistor and input voltage, the GS92A3 based buck converter has the relative constant frequency. Moreover, the GS92A3 can increase the duty-cycle automatically as input voltage falls down. Because of the constant on-time in each switching period, the converter maintains the relative frequency when the input voltage changes

At the beginning of each switching cycle, upper power MOSFET is turned on, after typical fixed on-time, the upper MOSFET is turned off, and then lower power MOSFET is turned on after internal dead time. The upper MOSFET will not be turned on at the beginning of next cycle until output voltage falls down below the preset voltage and the dead time passes. The same events repeat the following switching cycles. To avoid the surge inductor current during large load transient, a minimum Off-time is added. Typical minimum off-time is around 440ns. The too small on-time can affect soft-start and anti-noise ability, so in order to avoid the on-time too small to be eliminated; a minimum on-time is set to around 110ns. This should to be noted in the small duty applications.

#### **High Side Switch On-Time Count**

The on-time is decided by the external setting resistor, and the input voltage. Looking at the TON pin, the input voltage is converted to current which is inversely proportional to itself by dividing the external setting resistor. The input voltage-proportional current is used to charge an internal capacitor from zero volts. When the voltage between two terminals of the capacitor reaches to the internal setting voltage, on-time one-shot pulse is generated, and then upper power MOSFET is turned on.

We can count the on-time and switching frequency according to the equations below:

 $T_{ON} = (V_{OUT} \times R_{TON} \times 8p) / (V_{IN} - 0.8)$ 

for VOUT<=2.5V

 $T_{ON} = (R_{TON} \times 20p) / (V_{IN} - 0.8)$ 

for VOUT>2.5V

Then, the switching frequency is:

 $F_{sw} = V_{OUT} / (V_{IN} \times T_{ON})$ 

R<sub>TON</sub> is a resistor connected from the input supply (VIN) to the TON pin.

For heavy load (more than 8A) application, due to ground bounced and the high impedance of R<sub>TON</sub>, the TON pin should always be bypassed to GND using a several nF-order ceramic capacitor for reliable system operation.

# EN, PFMPWM Mode and Shutdown Soft-Discharge

The EN/DEM pin enables the power supply. When EN/DEM is tied to high voltage (over  $V_{\text{EN\_H}}$ ) the GS92A3 is enabled and diode-emulated mode (DEM, which is power save mode) will be also enabled. When the EN/DEM is floating or tri-stated, an internal tri-stated judged logic module will activate the controller and the DEM Mode will be disabled.

In DEM mode, when the loads goes low, GS92A3 starts power save mode in order to maintain the on-time and decrease the system clock frequency to skip PWM pulses for better efficiency. If DEM Mode is enabled, the GS92A3 zero crossing comparator will sense the



inductor current and judge its value by comparing the LX node (LX) to PGND. Once the LX node voltage is equal to the PGND node voltage, the converter will enter the DEM Mode and turn off the low side power MOSFET. As the load current is further decreased, it takes longer time to discharge the output capacitor to the level than required the next switching cycle. The on-time is kept the same as that in the heavy-load condition.

If the EN/DEM pin is pulled low, the GS92A3 internal logic will shutdown the switching clock and stop the buck converter, and Discharge Module works to discharge the related output voltage through the VOUT pin. This will ensure that the output is in a defined state next time when it is enabled. Since this is a soft discharge, that there are no dangerous negative voltage excursions to be concerned about. In order to maintain the correct function of the soft-discharge module, the chip power supply must be online.

### **Output Voltage Selection**

The output voltage is set by the feedback resistors R<sub>FB1</sub> and R<sub>FB2</sub> of Figure1a and Figure1b. The internal reference is 0.8V, so the voltage at the feedback pin is also 0.8V. Therefore the output can be set by the equation below:

$$V_{OUT} = (1 + R_{FB1}/R_{FB2}) \times 0.8V$$

#### **Current Limit**

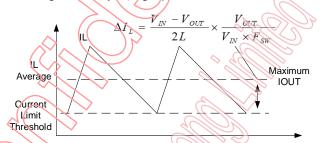
The GS92A3 uses the on-state resistance of the low-side power MOSFET as a current-sense resistor. In this case, the  $R_{CS}$  resistor between the LX pin and CS pin sets the over current threshold. This resistor  $R_{CS}$  is connected to a 20uA current source within the GS92A3 which is turned on when the low side power MOSFET turns on. When the voltage drop across the low side power MOSFET equals the voltage crossing the current limit resistor  $R_{CS}$ , positive current limit will activate. The high side Power MOSFET will not be

turned on until both the voltage drop across the sense element (low side power MOSFET) falls below the voltage across the R<sub>CS</sub> resistor and the output voltage falls to pre-set value. The current sensing circuit actually regulates the inductor valley current. This means that if the magnitude of the current-sense signal at CS pin is above the current-limit threshold, the PWM is not allowed to initiate a new switching cycle. The equation for the current limit threshold is as follows:

IL\_LIMIT=20uAxR<sub>CS</sub>/R<sub>DSC</sub>

Where, R<sub>DSL</sub> is the resistance of low side power MOSFET.

It is diagramed by the graph below:



Ensure that noise and DC errors do not corrupt the current-sense signal seen by CS and PGND. Mount the IC close t the low side power MOSFET and sense resistor with short, direct traces, making a Kelvin sense connection to the sense resistor.

### **Output Over-Voltage Protection**

When the output voltage rises up to 125% of the preset voltage, the internal fault-logic module delays about 20us and turns on the low side Power MOSFET. It stays latched on and the GS92A3 is latched off until Power Reset or EN Reset.

### Output Under-Voltage Protection

When the output voltage falls down to 45% of the preset voltage, the internal fault-logic module will delay about 20us and turns off both the high side and low side Power MOSFETs. Both switches stay latched off and the GS92A3 is latched off until Power Reset or EN Reset. During soft-start, the UVP will be blanked, until soft-start procedure finished. The blank time depended

Green Solution Technology Co., LTD.



on the value of the capacitor connected to SS Pin. But if the output voltage rises up above the UVP threshold tolerance during the counter period, the UVP counter is released immediately.

## **UVLO and Soft-Start**

An internal under voltage lockout (UVLO) module is used to sense the VCC power supply. The PWM converter is forbidden by the under voltage lockout module. When VCC rises about 4.15V, the GS92A3 will initial the control logic circuitries and soft-start ramping generator, and then allows switching to occur. When VCC falls down to about 3.85V, the PWM converter is forbidden again.

When VAIN rises about 5.5V, the LDO output voltage (VCC) of GS92A3 enables and regulates a 5.15V voltage. After VAIN falls down to 5.3V the LDO (VCC) will turn off.

After soft-start module starting, the GS92A3 converter will release the current limit threshold followed the soft-start ramp. After UVP blanking time the output under voltage protection is enabled.

#### **FB Short Protection**

Because the UVP protection is blanked during the soft-start period, if FB pin short to GND, the output voltage will increase continuously without OVP protection. It is a very dangerous condition. The GS92A3 build in a safety protection scheme to avoid this situation. When soft-start procedure begins, the GS92A3 monitors the SS Pin and FB Pin both, if the voltage of SS Pin is higher than 160mV and at the same time the voltage of FB Pin is lower than 80mV, after a few micro seconds delay, the fault logic will stop the switching cycle and latch on. Only Power on Reset and EN Reset can release this latch condition.

#### **VOUT Pin**

The Vout Pin offers feedback information of output voltage. This information makes the ton more accurate, so the switching frequency variation is very

small even when the GS92A3 operates on very wide input voltage range. When any fault condition occurs, the Vout Pin provides a discharge path from output to gnd.

#### **External Devices Selection**

For loop stability, the 0 dB frequency (f0), defined in the follow equation:

follow equation: 
$$f_0 = \frac{1}{2\pi \times RESR \times C_{OUT}} \le \frac{f_{SW}}{4}$$

The loop stability is determined by the output capacitor. Specialty polymer capacitors have C<sub>OUT</sub> in the order of several 100uF and RESR in range of 10mohm is recommended. However, ceramic capacitors have f0 at more than 700 KHz, which is not recommended.

In order for the right regulate manner, the ripple voltage at the feedback pin (FB), should be approximately 15mV: This generates Vripple= (V<sub>OUT</sub>/0.8) ×15mV at the output node. The output capacitor RESR should meet this equation.

The external device selection is list below:

### Choose Feedback Voltage Divider Resistor

Set R<sub>FB2</sub>=1K~20K ohm

$$R_{FB1} = \frac{(V_{OUT} - 0.8)}{0.8} \times R_{FB2}$$

### **Choose RTON**

$$T_{ON(Max)} = \frac{1}{f_{SW}} \times \frac{V_{OUT}}{V_{IN(Min)}}$$

$$R_{TON(MAX)} = (V_{IN} - 0.8) \times 375K$$

#### **Choose Inductor**

Set the ripple current approximately 1/4 to 1/2 of the maximum output current. 1/3 is recommended. The recommended inductor can be calculated from the output current, indicated by formula below

$$L_{IND} = \frac{3}{I_{IOUT(max)} \times f} \times \frac{(V_{IN(max)} - V_{OUT}) \times V_{OUT}}{V_{IN(max)}}$$

For applications that require fast transient response

Green Solution Technology Co., LTD.



with minimum VOUT overshoot, consider a smaller inductance than above. The cost of a small inductance value is higher steady state ripple, larger line regulation, and higher switching loss.

### **Choose Output Capacitors**

$$RESR = \frac{1}{I_{ripple}} \times \frac{V_{OUT}}{0.8} \times 0.015$$

$$\approx \frac{3}{I_{OUT(max)}} \times \frac{V_{OUT}}{0.8} \times 0.015$$

$$RESR \approx \frac{V_{OUT}}{I_{OUT(max)}} \times 75 (mohm)$$

Organic semiconductor capacitors are recommended.

### **Choose Soft-Start Capacitor**

When SS ramp rise up to about 1.6V, the chip thinks the soft-start procedure is over, and then, release the UVP protection function. At the same time, the VOUT voltage will reach the target set by the FB resistor divider. So, the total soft-start time is defined by the formula below:

$$T_{\rm SS} = \frac{1.6 \times C_{\rm SS}}{I_{\rm SS}} = 1.6 \times 10^8 \times C_{\rm SS} \, (\rm ms)$$

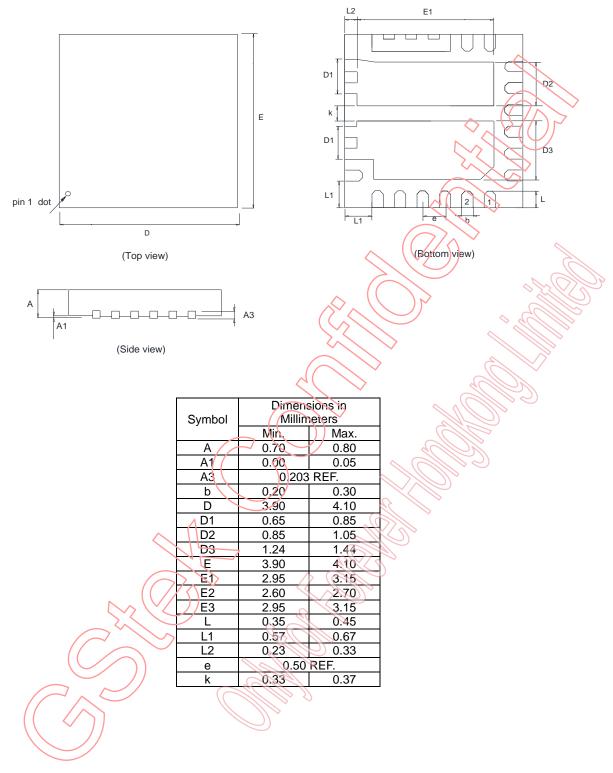
Where, the unit of Tss is mS.

For example, the typical Tss is equal to 1.6mS with  $10nF\ C_{SS}$ .





# Package Dimensions, TQFN23-4x4



### <u>Note</u>

1. Min.: Minimum dimension specified.

2. Max.: Maximum dimension specified.

3. REF.: Reference. Normal/Regular dimension specified for reference.





Please read the notice stated in this preamble carefully before Admission e accessing any contents of the document attached. Admission of GStek's statement therein is presumed once the document is released to the receiver.

Notice:

Firstly, GREEN SOLUTION CO., LTD. (GStek) reserves the right to make corrections, modifications, enhancements, improvements, and other changes to its information herein without notice. And the aforesaid information does not form any part or parts of any quotation or contract between GStek and the information receiver.

Further, no responsibility is assumed for the usage of the aforesaid information. GStek makes no representation that the interconnect of its circuits as described herein will not infringe on exiting or future patent rights and other intellectual property rights, nor do the descriptions contained herein express or imply that any licenses under any GStek patent right, copyright, mask work right, or other GStek intellectual property right relating to any combination, machine, or process in which GStek products or services are used.

Besides, the product in this document is not designed for use in life support appliances, devices, or systems where malfunction of this product can reasonably be expected to result in personal injury. GStek customers' using or selling this product for use in such applications shall do so at their own risk and agree to fully indemnify GStek for any damage resulting from such improper use or sale.

At last, the information furnished in this document is the property of GStek and shall be treated as highly confidentiality; any kind of distribution, disclosure, copying, transformation or use of whole or parts of this document without duly authorization from GStek by prior written consent is strictly prohibited. The receiver shall fully compensate GStek without any reservation for any losses thereof due to its violation of GStek's confidential request. The receiver is deemed to agree on GStek's confidential request therein suppose that said receiver receives this document without making any expressly opposition. In the condition that aforesaid opposition is made, the receiver shall return this document to GStek immediately without any delay.